



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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**PRINTED CIRCUIT BOARDS**

**01**

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 105 FR4 35 L41.35 P18\_06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_105\_FR4\_35\_L41.35\_p18\_06**

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		
	60 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-2	180 $\mu$	Prepreg		
	35 $\mu$	Copper		
	410 $\mu$	L-FR4		
Layer-99	60 $\mu$	Prepreg		
	60 $\mu$	Prepreg		
	35 $\mu$	Copper		

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